

4-Channel ESD Array in CSP

CM1244

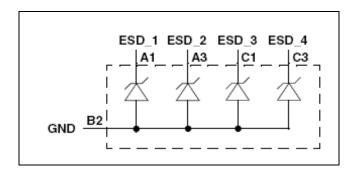
Features

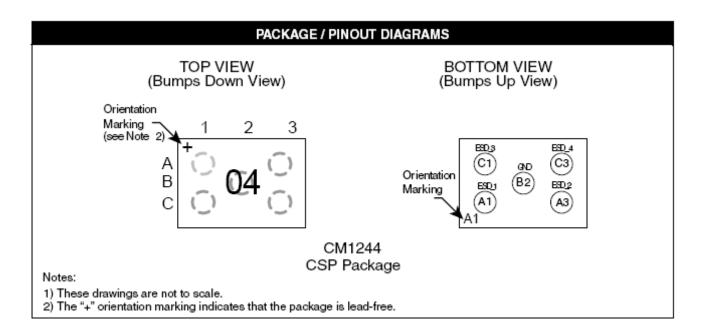
- Four channels of ESD protection
- ±15kV ESD protection on each channel (IEC 61000-4-2 Level 4, contact discharge)
- ±30kV ESD protection on each channel (HBM)
- Chip Scale Package features extremely low lead inductance for optimum ESD protection
- 5-bump, 0.760mm x 1.053mm footprint, 0.4mm pitch, Chip Scale Package (CSP)
- Lead-free
- OptiGuard[™] coating for improved reliability at assembly

Applications

- ESD protection for sensitive electronic equipment
- I/O port and keypad and button circuitry protection for portable devices
- Can be used for EMI filtering when combined with external series resistance
- · Wireless handsets
- Handheld PCs/PDAs
- MP3 Players
- Digital Camcorders
- Notebooks
- Desktop PCs

Block Diagram





PIN DESCRIPTIONS					
PIN	NAME	DESCRIPTION			
A1	ESD_1	ESD Channel1			
А3	ESD_2	ESD Channel 2			
B2	GND	Device Ground			
C1	ESD_3	ESD Channel 3			
СЗ	ESD_4	ESD Channel 4			

Ordering Information

PART NUMBERING INFORMATION						
		Lead-free Finish				
Bumps	Package	Ordering Part Number ¹	Part Marking			
5	CSP	CM1244-04CP	04			

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

Specifications

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	RATING	UNITS				
Storage Temperature Range	-65 to +150	Ç				
DC Package Power Rating	200	mW				

STANDARD OPERATING CONDITIONS							
PARAMETER	RATING	UNITS					
Operating Temperature Range	-40 to +85	∞					

	ELECTRICAL OPERATING CHARACTERISTICS ¹								
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS			
V _{DIODE}	Diode Reverse Breakdown Voltage	$I_{\text{DIODE}} = 10 \mu A$	5.5			V			
I _{LEAK}	Diode Leakage Current	V _{IN} =3.3V, T _A =25℃			100	nA			
V _{SIG}	Signal Voltage Positive Clamp Negative Clamp	I _{DIODE} = 10mA	5.6 -1.5	6.8 -0.8	9.0 -0.4	V			
V _{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2	Note 2	±30 ±15			kV kV			
V _{CL}	Clamping Voltage during ESD Discharge MIL-STD-883 (Method 3015), 8kV Positive Transients Negative Transients	Note 2		+15 -8		V			
C _{DIODE}	Diode Capacitance	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	22	27	32	pF			

Note 1: $T_A = -40$ to +85 °C unless otherwise specified.

Note 2: ESD applied to input and output pins with respect to GND, one at a time.

Application Information

Refer to Application Note AP-217, "The Chip Scale Package," for a detailed description of Chip Scale Packages offered by California Micro Devices.

Performance Information

Diode Characteristics (nominal conditions unless specified otherwise)

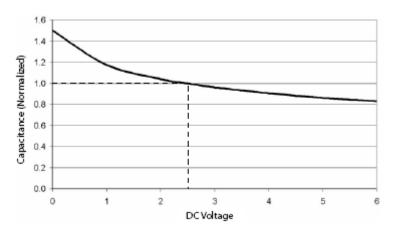


Figure 1. Typical Diode Capacitance VS. Input Voltage (normalized to 2.5VDC)

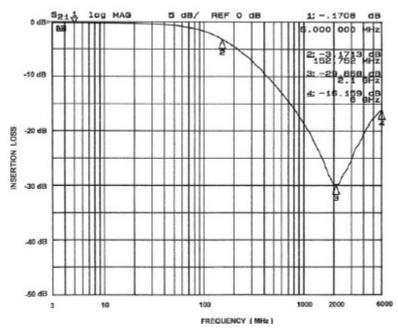


Figure 2. Frequency Response (single channel vs. GND, in 50Ω system)

Mechanical Details

CSP Mechanical Specifications

The CM1244 is available in a custom Chip Scale Package (CSP). Dimensions are presented below.

PACKAGE DIMENSIONS								
Pack	age	Custom CSP						
Bumps		5						
Dim	М	illimete	rs	Inches				
Diiii	Min	Nom	Max	Min	Nom	Max		
A 1	0.715	0.760	0.805	0.0281	0.0299	0.0317		
A2	1.008	1.053	1.098	0.0397	0.0415	0.0432		
B1	0.395	0.400	0.405	0.0156	0.0157	0.0159		
B2	0.195	0.200	0.205	0.0076	0.0078	0.080		
В3	0.342	0.347	0.352	0.0134	0.0136	0.0138		
B4	0.342	0.347	0.352	0.0134	0.0136	0.0138		
C1	0.130	0.180	0.230	0.0051	0.0071	0.0091		
C2	0.130	0.180	0.230	0.0051	0.0071	0.0091		
D1	0.545	0.615	0.685	0.0215	0.0242	0.0268		
D2	0.368	0.419	0.470	0.0145	0.0165	0.0185		
# per tape and reel				3500 pied	ces			

Mechanical Package Diagrams

BOTTOM VIEW

A1

C1

SIDE
VIEW

0.27mm DIA

B

96.8/2.6/0.6 Sn/Ag/Cu (Lead-free)
SOLDER BUMPS

D1

D2

Controlling dimension: millimeters

Package Dimensions for CM1244 Chip Scale Package

DIMENSIONS IN MILLIMETERS

Coating

CSP Tape and Reel Specifications

PART NUMBER	CHIP SIZE (mm)	POCKET SIZE (mm) B _o X A _o X K _o	TAPE WIDTH W	REEL DIAMETER	QTY PER REEL	P _o	P ₁
CM1244	1.05 X 0.76 X 0.615	1.42 X 1.07 X 0.74	8mm	178mm (7")	3500	4mm	4mm

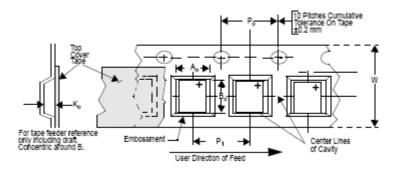


Figure 3. Tape and Reel Mechanical Data

CM1244

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